

QUANTIFI PHOTONICS™

SCALING INTEGRATED PHOTONICS FOR THE AI
REVOLUTION - A TESTING PERSPECTIVE

Integrated Photonics Ecosystem Series

Kees Propstra

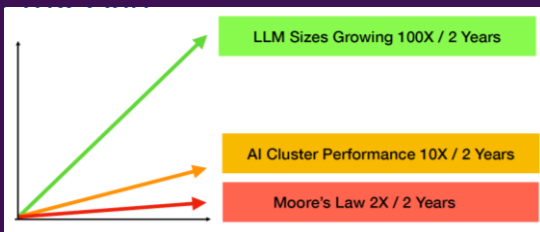
OUTLINE

Problem statement

Photonics test overview

Examples

Conclusions

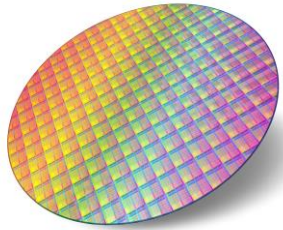


Bechtolsheim, PECC Summit'23

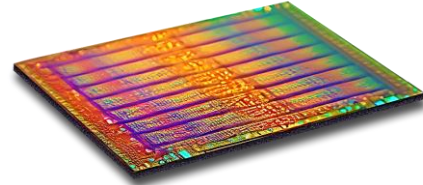


PROBLEM STATEMENT

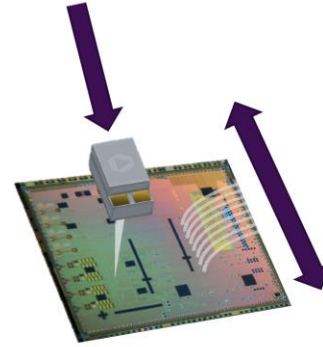
Production Stages



Wafer Sort



Die/PIC



Assembly

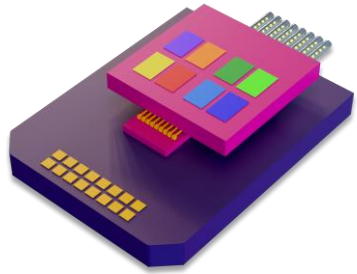


Packaged Test

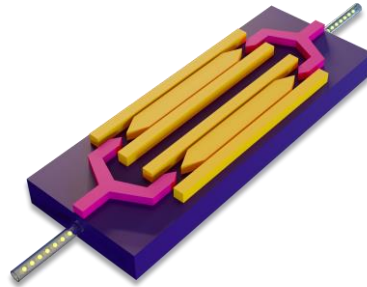
Product Life Cycle



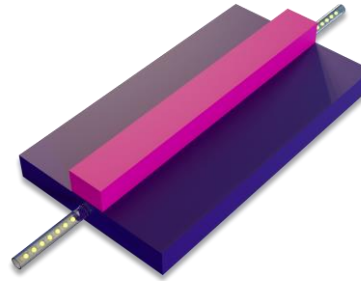
PHOTONIC DEVICES OVERVIEW



External Laser Source



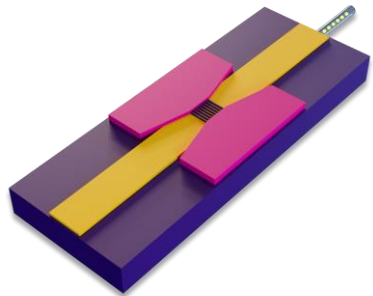
Modulator



Waveguide



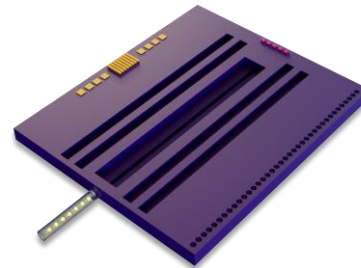
Grating Coupler



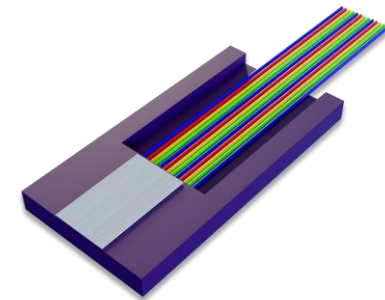
Laser Diode



Ring Resonator



Receiver

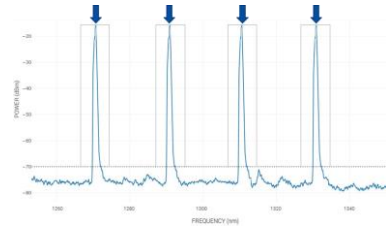


Fiber Array

MEASUREMENTS OVERVIEW

Passive

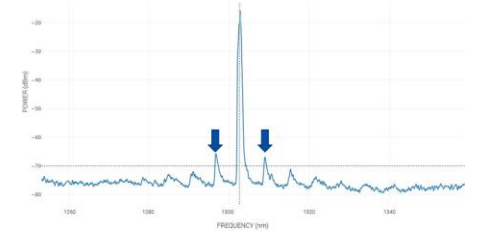
- Insertion loss
- Return loss
- Wavelength dependence
- Polarization dependence



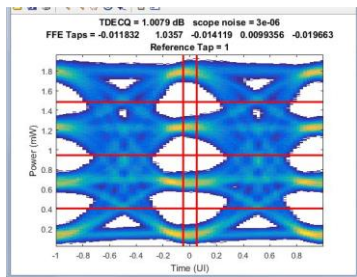
Waveguides
Mux/demux
Grating coupler

Active

- Fiber array alignment
- Power levels
- Optical spectrum/SMSR/OSNR
- Line width
- Modulation depth
- LIV-curve
- Photocurrent/linearity/responsivity
- RIN measurement



Laser diode
Ring resonator
Modulator
Receiver
Fiber array



High-speed

- Eye diagram
- BER
- Receiver sensitivity
- S-parameters

Modulator
Receiver
Module

INSTRUMENTS OVERVIEW

Input



Fixed Laser



CW-CWDM
ELS



Tunable Laser
Swept or Step



POL Controller



Broadband
Source (LED)

Support



Optical Amplifier



VOA



50/50 Splitter



1xN Switch

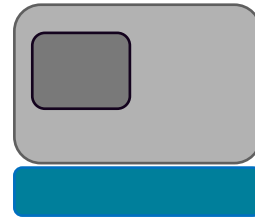


SMU



VST

Output



LCA



OPM



OSA



O2E



BERT

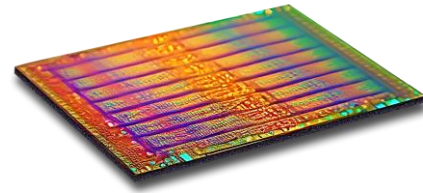


Photo Current
Amplifier & Meter

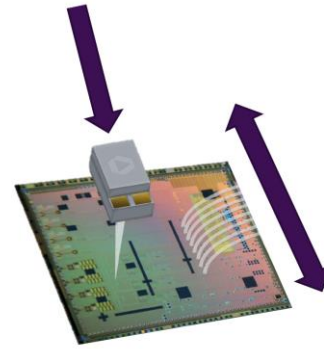


DSO

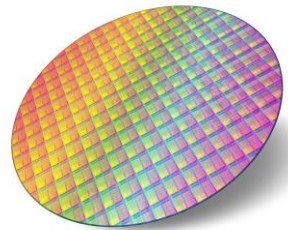
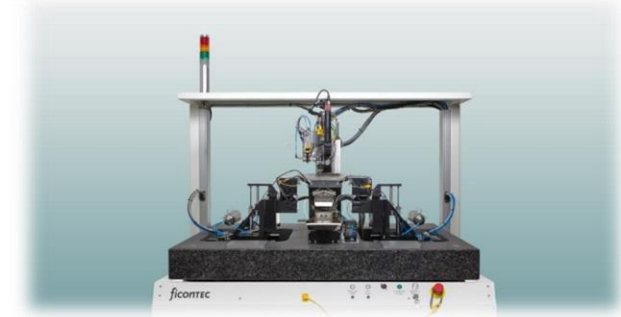
WHAT TO TEST WHEN?



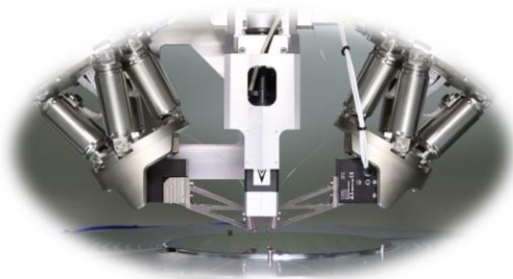
Die/PIC



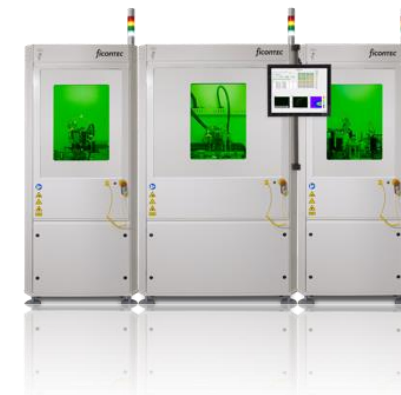
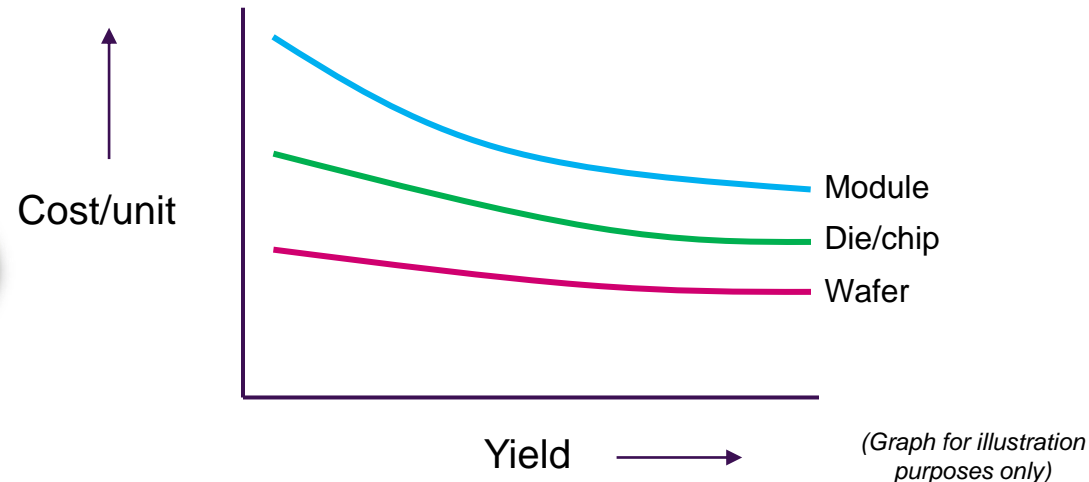
Assembly



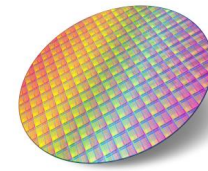
Wafer Sort



Packaged Test



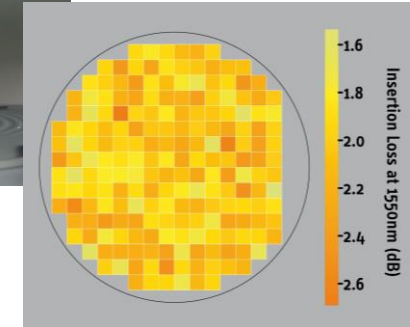
WAFER LEVEL INSPECTION/TESTING



Parametric testing - wavelength and polarization dependent behavior

Setup with wafer handler and a probing system:

- Inject the optical signal into the wafer
- Power and activate DUTs
- Measure the optical signal out of the DUT
- High-speed characterization desired (known-good-die)



FIRST PHASE (pre-production)

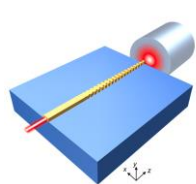
Cover all performance parameters (including high-speed) to guarantee known-good-die.

SECOND PHASE (production)

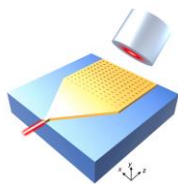
Cover most performance parameters, based on statistical sampling to guarantee known-good-die.

DATA CORRELATION

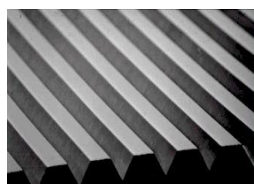
- Reduce the number of different tests (scale down test coverage)
- Reduce the percentage of devices tested
- Front load the testing (product life cycle, manufacturing stages)



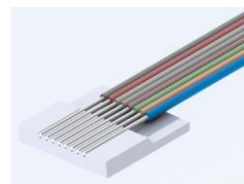
Edge Coupling



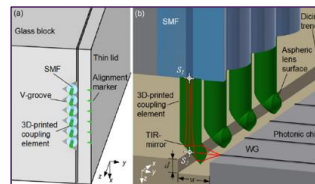
Grating Coupling



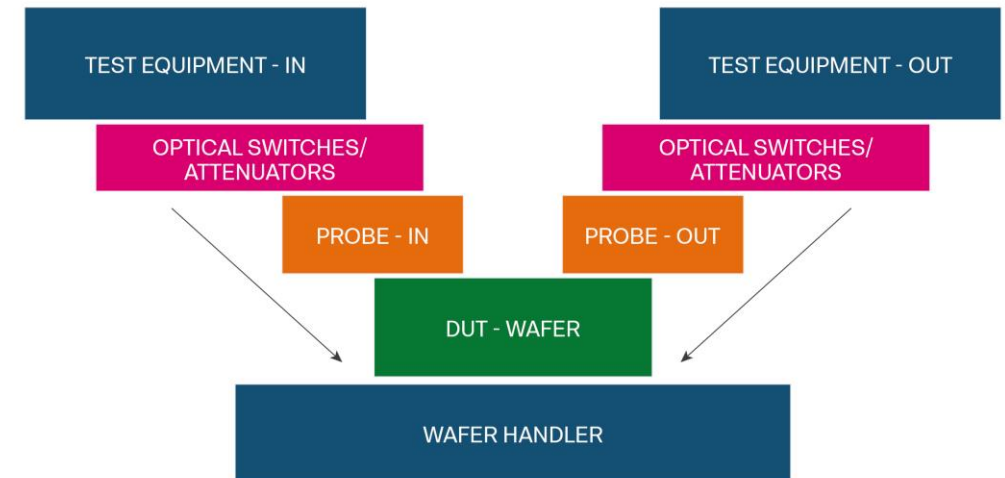
V-grooves



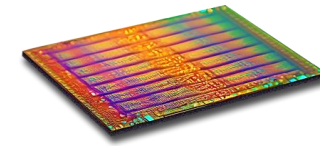
Fiber Array Unit



3D-printed lens periscopes

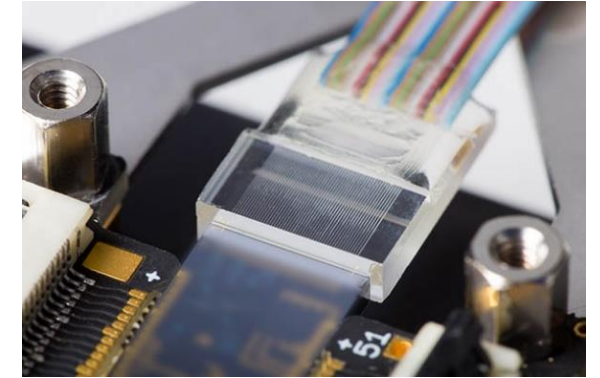


DIE/PIC- FIBER ARRAY ALIGNMENT AND ASSEMBLY



Guaranteed known-good-die from previous stage

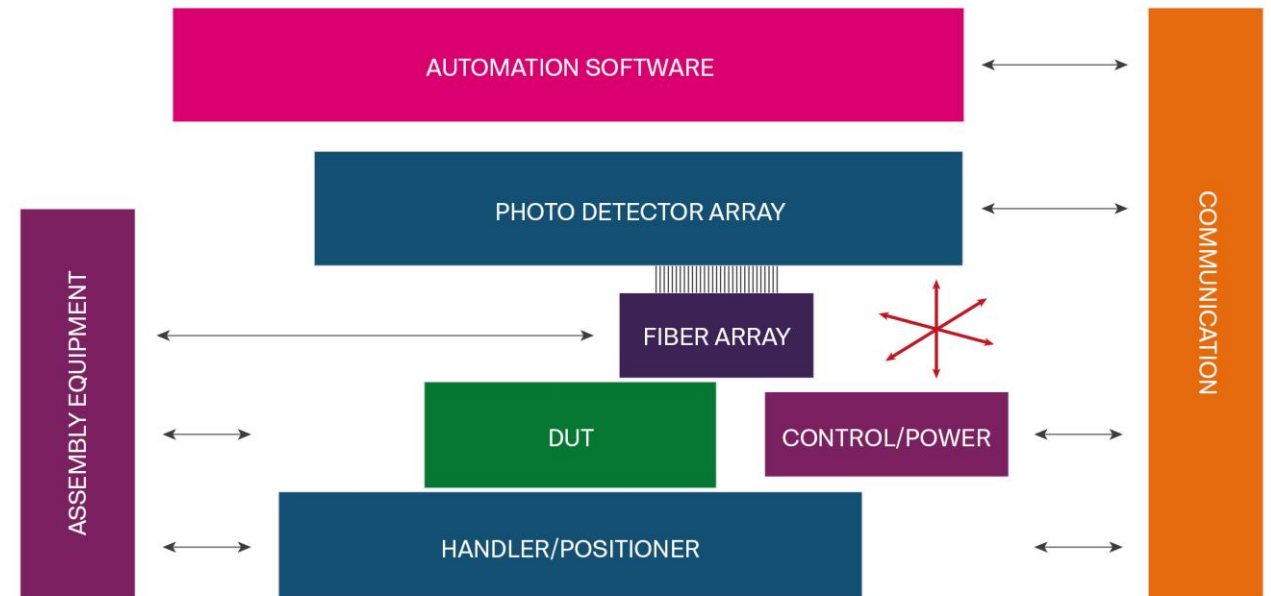
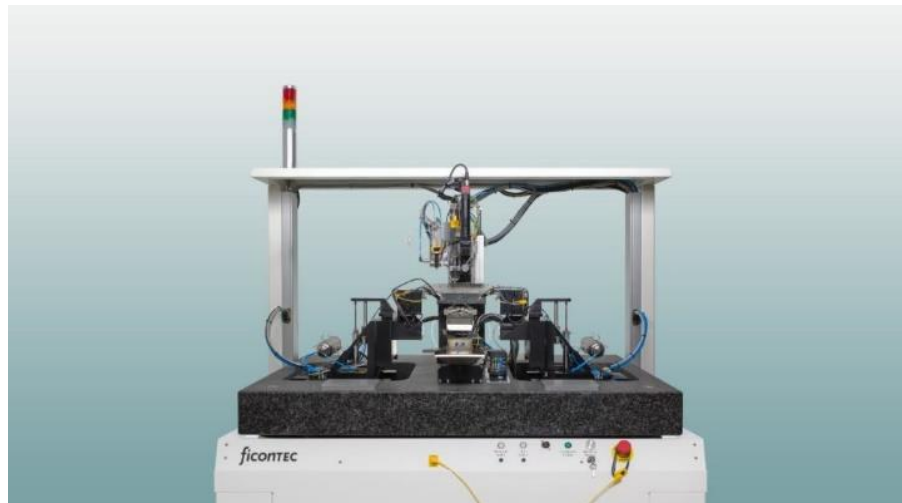
- Perform fiber array alignment and other assembly steps
- Optimum fiber array position while curing the adhesive between DUT and fiber array
- High yield, low risk - validating that all channels of the DUT are still performing within spec
 - Parallel testing for quick screen
- If assembly steps are lower yield (higher risk) then other tests may be appropriate



288 channel optical power meter



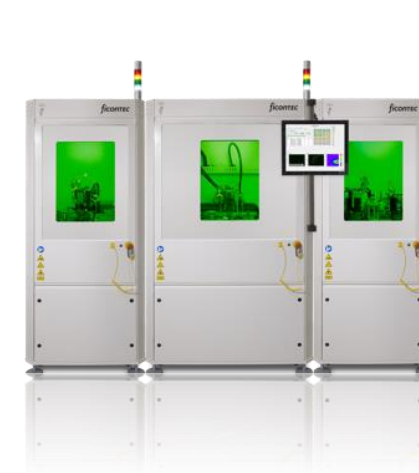
Power-1410-288-MTP-EPIQ



MODULE TESTING

Final step of the manufacturing cycle

- At-speed optimization and test for spec compliance
- MSA form factor QSFP-DD, OSFP-XD, OIF 3.2T CPO
- Test fixture for DUT control and high-speed signal access
- Thermal stream or TEC for temperature control
- Final tweaking of device parameters to maximize yield



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FIRST PHASE (pre-production)

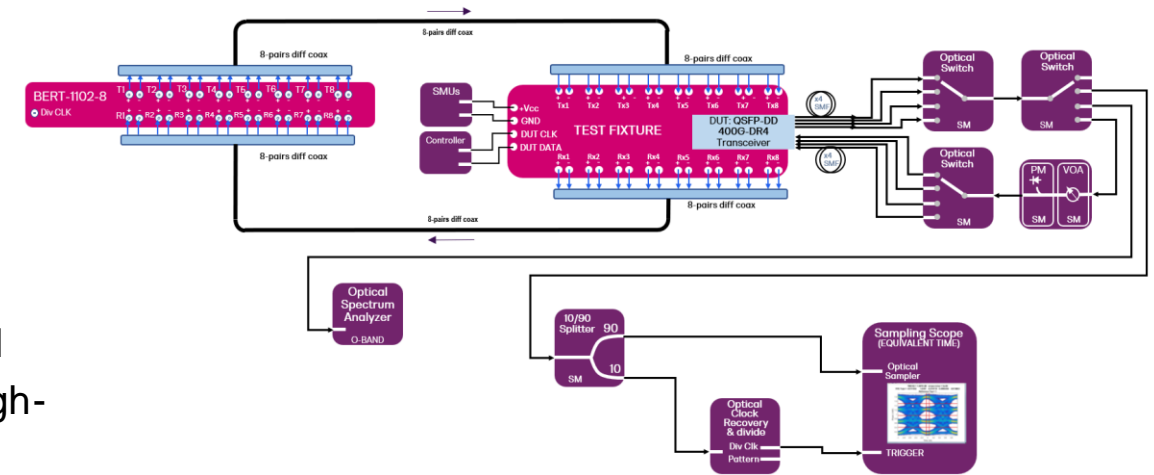
Cover all performance parameters to guarantee product meets all requirements *over temperature*.

SECOND PHASE (production)

Cover most performance parameters to guarantee product meets all requirements. Thermal validation hopefully can be avoided in the high-volume stage.

DATA CORRELATION

- Scale down test coverage
- 100% testing (devices/channels) still seems desirable
 - Parallel testing!



RECIPE FOR SUCCESS

FULL COMPLEMENT of photonics test functions

FLEXIBLE platform to transition from R&D to validation/characterization, pilot and finally mass production

INTEGRATION into wafer probing, assembly and alignment equipment

SCALABLE to high-channel-count parallel testing

HIGH-DENSITY to pack a lot of test instruments in a small space

OPTIMIZED test flow (time is money)



ECOSYSTEM ASKS

STANDARDIZATION desired/required?

Optical signal access

Measurements and test plan

Hardware framework

Software framework

Powered by **PXI**
Systems Alliance

gRPC



* Images courtesy of ficonTEC